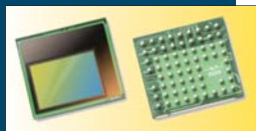
2019 Flip Chip and WLP:
Trends and Market Projections



Fan-in wafer level package (WLP) and fan-out WLP continue to show strong growth. This report provides examples of the many products using WLP, including the supplier, number of WLPs in each product, and dimensions. Demand for flip chip in applications ranging from large die for AI accelerators to small die for amplifiers and filters is covered. Cu pillar is increasingly used for many devices. Demand continues for both 300mm and 200mm bumping and market projections in units and wafers are provided. An analysis of bumping, WLP, and FO-WLP capacity is presented for each segment by geographic region, technology, and wafer size. Panel processing developments, applications, and production plans are presented. Flip chip equipment and assembly methods are discussed. A set of 90 PowerPoint slides is included with the detailed analysis.

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